

Amendments to the Claims:

This listing of claims represent all of the claims in this application:

Listing of Claims:

Claims 1 - 12 (canceled)

Claim 13 (original) A method of making a PCB, said method comprising:

providing a first multilayered portion including at least one dielectric layer and at least one conductive plane wherein said conductive plane includes signal lines capable of having signals pass therealong at a first frequency;

providing a second multilayered portion adapted for having a plurality of electronic components electrically coupled thereto, said second multilayered portion including at least one dielectric layer and at least one conductive signal plane wherein said conductive signal plane of said second multilayered portion includes signal lines capable of having signals pass therealong at a higher frequency than said first frequency to thereby provide a high speed connection between at least two of said electrical components; and

bonding said first and second multilayered portions to form said PCB.

Claim 14. (original). The method of claim 13 further including providing a conductive through hole within said second multilayered portion prior to said bonding of said first and second multilayered portions.

Claim 15. (original). The method of claim 13 wherein said bonding is accomplished by lamination.